

IS61WV12824

128K x 24 HIGH-SPEED CMOS STATIC RAM WITH 3.3V SUPPLY

AUGUST 2017

FEATURES

- High-speed access time: 8, 10 ns
- High-performance, low-power CMOS process
- TTL compatible interface levels
- Single power supply
VDD 3.3V \pm 5% for 8ns
VDD 2.4V to 3.6V for 10ns
- Fully static operation: no clock or refresh required
- Three state outputs
- Available in 119-pin Ball Grid Array (BGA) and 100-pin QFP packages.
- Industrial temperature available
- Lead-free available

DESCRIPTION

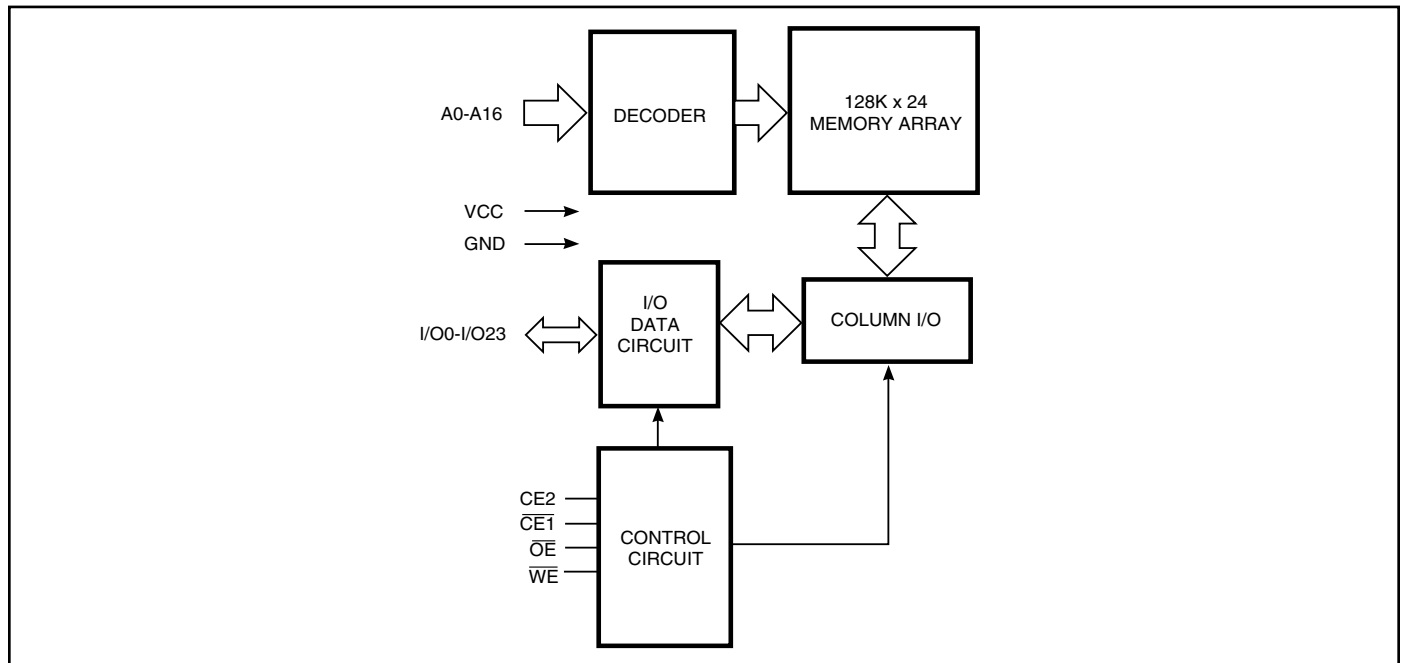
The *ISSI* IS61WV12824 is a high-speed, static RAM organized as 131,072 words by 24 bits. It is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields access times as fast as 8 ns with low power consumption.

When $\overline{CE1}$ is HIGH and CE2 is LOW (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs, $\overline{CE1}$, CE2 and \overline{OE} . The active LOW Write Enable (\overline{WE}) controls both writing and reading of the memory.

The IS61WV12824 is packaged in the JEDEC standard 119-pin BGA and 100-pin QFP.

FUNCTIONAL BLOCK DIAGRAM



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- a.) the risk of injury or damage has been minimized;
- b.) the user assume all such risks; and
- c.) potential liability of Integrated Silicon Solution, Inc is adequately protected under the circumstances

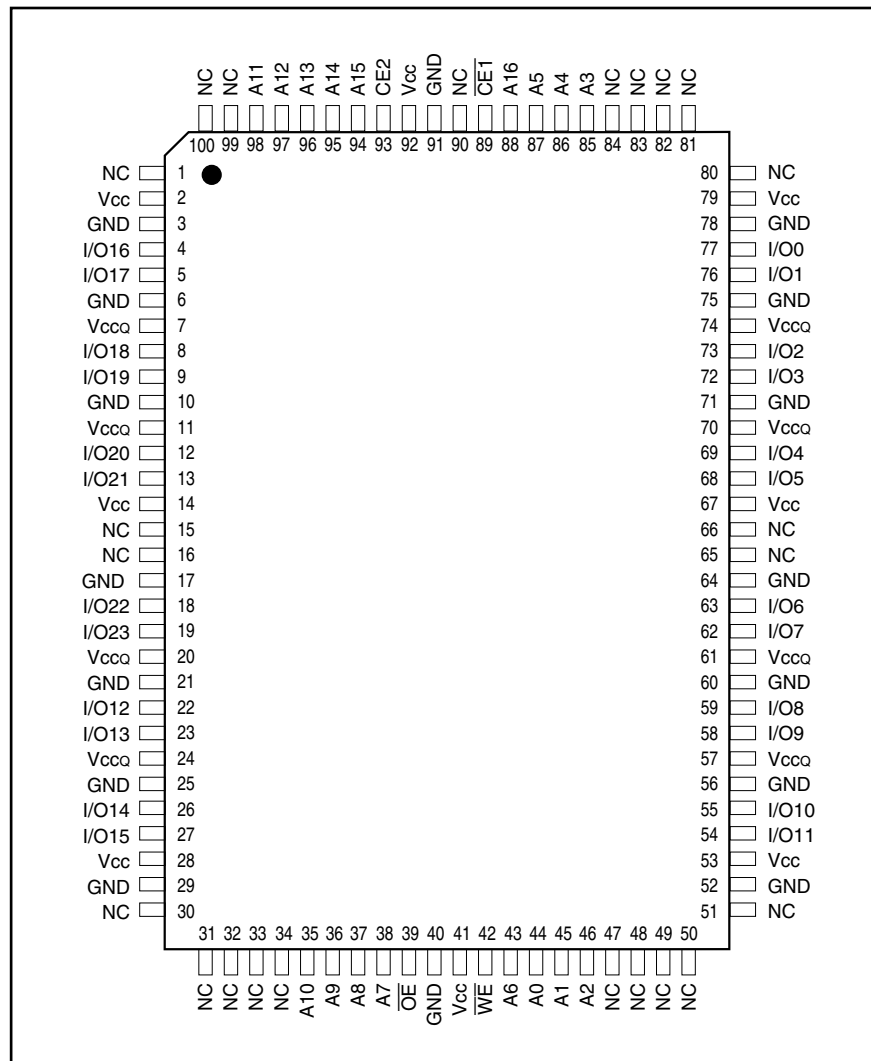
PIN CONFIGURATION - 119-pin BGA

	1	2	3	4	5	6	7
A	NC	A11	A14	A15	A16	A4	NC
B	NC	A12	A13	$\overline{CE1}$	A5	A3	NC
C	I/O16	NC	CE2	NC	NC	NC	I/O0
D	I/O17	V _{CC}	GND	GND	GND	V _{CC}	I/O1
E	I/O18	GND	V _{CC}	GND	V _{CC}	GND	I/O2
F	I/O19	V _{CC}	GND	GND	GND	V _{CC}	I/O3
G	I/O20	GND	V _{CC}	GND	V _{CC}	GND	I/O4
H	I/O21	V _{CC}	GND	GND	GND	V _{CC}	I/O5
J	V _{CC}	GND	V _{CC}	GND	V _{CC}	GND	V _{CC}
K	I/O22	V _{CC}	GND	GND	GND	V _{CC}	I/O6
L	I/O23	GND	V _{CC}	GND	V _{CC}	GND	I/O7
M	I/O12	V _{CC}	GND	GND	GND	V _{CC}	I/O8
N	I/O13	GND	V _{CC}	GND	V _{CC}	GND	I/O9
P	I/O14	V _{CC}	GND	GND	GND	V _{CC}	I/O10
R	I/O15	NC	NC	NC	NC	NC	I/O11
T	NC	A10	A8	\overline{WE}	A0	A1	NC
U	NC	A9	A7	\overline{OE}	A6	A2	NC

PIN DESCRIPTIONS

A0-A16	Address Inputs
I/O0-I/O23	Data Inputs/Outputs
$\overline{CE1}$	Chip Enable Input LOW
CE2	Chip Enable Input HIGH
\overline{OE}	Output Enable Input
\overline{WE}	Write Enable Input
NC	No Connection
V _{CC}	Power
GND	Ground

PIN CONFIGURATION
100-Pin QFP



PIN DESCRIPTIONS

A0-A16	Address Inputs
I/O0-I/O23	Data Inputs/Outputs
$\overline{CE1}$	Chip Enable Input LOW
CE2	Chip Enable Input HIGH
\overline{OE}	Output Enable Input
\overline{WE}	Write Enable Input
NC	No Connection
Vcc	Power
Vccq	I/O Power
GND	Ground

TRUTH TABLE

Mode	\overline{WE}	$\overline{CE1}$	CE2	\overline{OE}	I/O0-I/O23	Vcc Current
Not Selected	X	H	X	X	High-Z	ISB1, ISB2
	X	X	L	X		
Output Disabled	H	L	H	H	High-Z	Icc
Read	H	L	H	L	DOUT	Icc
Write	L	L	H	X	DIN	Icc

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	Value	Unit	
V _{CC}	Power Supply Voltage Relative to GND	-0.5 to 5.0	V	
V _{TERM}	Terminal Voltage with Respect to GND	-0.5 to V _{CC} + 0.5	V	
T _{STG}	Storage Temperature	-65 to + 150	°C	
T _{BIAS}	Temperature Under Bias:	Com.	-10 to + 85	°C
		Ind.	-45 to + 90	°C
P _T	Power Dissipation	2.0	W	
I _{OUT}	DC Output Current	±20	mA	

Note:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

OPERATING RANGE

Range	Ambient Temperature	V _{CC} (8 ns)	V _{CC} (10 ns)
Commercial	0°C to +70°C	3.3V ± 5%	2.4V ~ 3.6V
Industrial	-40°C to +85°C	3.3V ± 5%	2.4V ~ 3.6V

Note:

1. When operated in the range of 2.4V~3.6V, the device meets 10ns. When operated in the range of 3.3V ± 5%, the device meets 8ns.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 3.3V \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$V_{DD} = \text{Min.}, I_{OH} = -4.0 \text{ mA}$	2.4	—	V
V_{OL}	Output LOW Voltage	$V_{DD} = \text{Min.}, I_{OL} = 8.0 \text{ mA}$	—	0.4	V
V_{IH}	Input HIGH Voltage		2	$V_{DD} + 0.3$	V
V_{IL}	Input LOW Voltage ⁽¹⁾		-0.3	0.8	V
I_{LI}	Input Leakage	$GND \leq V_{IN} \leq V_{DD}$	-2	2	μA
I_{LO}	Output Leakage	$GND \leq V_{OUT} \leq V_{DD}$, Outputs Disabled	-2	2	μA

Note:

- $V_{IL} (\text{min.}) = -0.3V \text{ DC}$; $V_{IL} (\text{min.}) = -2.0V \text{ AC}$ (pulse width 2.0 ns). Not 100% tested.
 $V_{IH} (\text{max.}) = V_{DD} + 0.3V \text{ DC}$; $V_{IH} (\text{max.}) = V_{DD} + 2.0V \text{ AC}$ (pulse width 2.0 ns). Not 100% tested.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 2.4V-3.6V$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$V_{DD} = \text{Min.}, I_{OH} = -1.0 \text{ mA}$	1.8	—	V
V_{OL}	Output LOW Voltage	$V_{DD} = \text{Min.}, I_{OL} = 1.0 \text{ mA}$	—	0.4	V
V_{IH}	Input HIGH Voltage		2.0	$V_{DD} + 0.3$	V
V_{IL}	Input LOW Voltage ⁽¹⁾		-0.3	0.8	V
I_{LI}	Input Leakage	$GND \leq V_{IN} \leq V_{DD}$	-2	2	μA
I_{LO}	Output Leakage	$GND \leq V_{OUT} \leq V_{DD}$, Outputs Disabled	-2	2	μA

Note:

- $V_{IL} (\text{min.}) = -0.3V \text{ DC}$; $V_{IL} (\text{min.}) = -2.0V \text{ AC}$ (pulse width 2.0 ns). Not 100% tested.
 $V_{IH} (\text{max.}) = V_{DD} + 0.3V \text{ DC}$; $V_{IH} (\text{max.}) = V_{DD} + 2.0V \text{ AC}$ (pulse width 2.0 ns). Not 100% tested.

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	Test Conditions		-8 ns		-10 ns		Unit
				Min.	Max.	Min.	Max.	
I _{CC}	V _{CC} Dynamic Operating Supply Current	V _{CC} = Max., I _{OUT} = 0 mA, f = f _{MAX}	Com.	—	110	—	90	mA
			Ind.	—	115	—	95	
I _{SB1}	TTL Standby Current (TTL Inputs)	V _{CC} = Max., V _{IN} = V _{IH} or V _{IL} , f = max. CE1 ≥ V _{IH} , CE2 ≤ V _{IL}	Com.	—	30	—	30	mA
			Ind.	—	35	—	35	
I _{SB2}	CMOS Standby Current (CMOS Inputs)	V _{CC} = Max., CE1 ≥ V _{CC} - 0.2V, CE2 ≤ 0.2V, V _{IN} ≥ V _{CC} - 0.2V, or V _{IN} ≤ 0.2V, f = 0	Com.	—	20	—	20	mA
			Ind.	—	25	—	25	

Note:

1. At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

CAPACITANCE⁽¹⁾

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{OUT}	Input/Output Capacitance	V _{OUT} = 0V	8	pF

Note:

1. Tested initially and after any design or process changes that may affect these parameters.

AC TEST CONDITIONS

Parameter	Unit	Unit
	(2.4V-3.6V)	(3.3V ± 5%)
Input Pulse Level	0.4V to V _{DD} -0.3V	0.4V to V _{DD} -0.3V
Input Rise and Fall Times	1.5ns	1.5ns
Input and Output Timing and Reference Level (V _{Ref})	V _{DD} /2	V _{DD} /2 + 0.05
Output Load	See Figures 1 and 2	See Figures 1 and 2

AC TEST LOADS

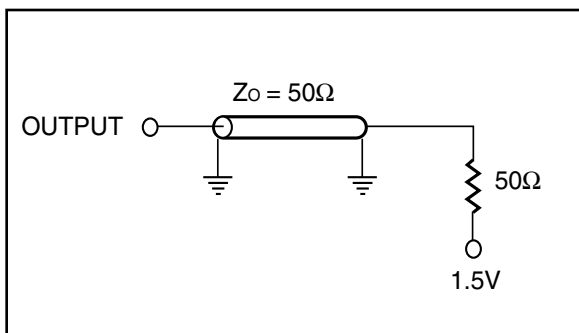


Figure 1

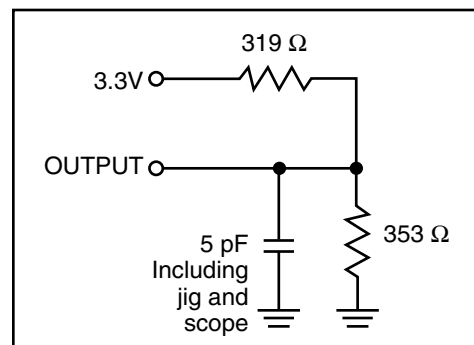


Figure 2

READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

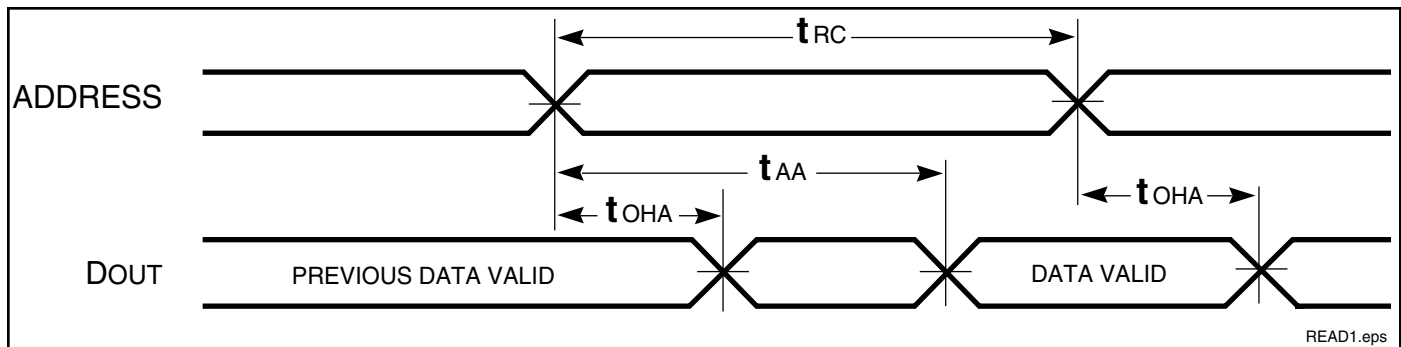
Symbol	Parameter	-8		-10		Unit
		Min.	Max.	Min.	Max.	
t _{RC}	Read Cycle Time	8	—	10	—	ns
t _{AA}	Address Access Time	—	8	—	10	ns
t _{OH}	Output Hold Time	2.5	—	2.5	—	ns
t _{ACE}	$\overline{CE1}$ Access Time	8	—	—	10	ns
t _{ACE2}	CE2 Access Time					
t _{DOE}	\overline{OE} Access Time	—	5.5	—	6.5	ns
t _{HZOE⁽²⁾}	\overline{OE} to High-Z Output	0	3	0	4	ns
t _{LZOE⁽²⁾}	\overline{OE} to Low-Z Output	0	—	0	—	ns
t _{HZCE⁽²⁾}	$\overline{CE1}$ to High-Z Output	0	3	0	4	ns
t _{HZCE2⁽²⁾}	CE2 to High-Z Output					
t _{LZCE⁽²⁾}	\overline{CE} to Low-Z Output	3	—	3	—	ns
t _{LZCE2⁽²⁾}	CE2 to Low-Z Output					

Notes:

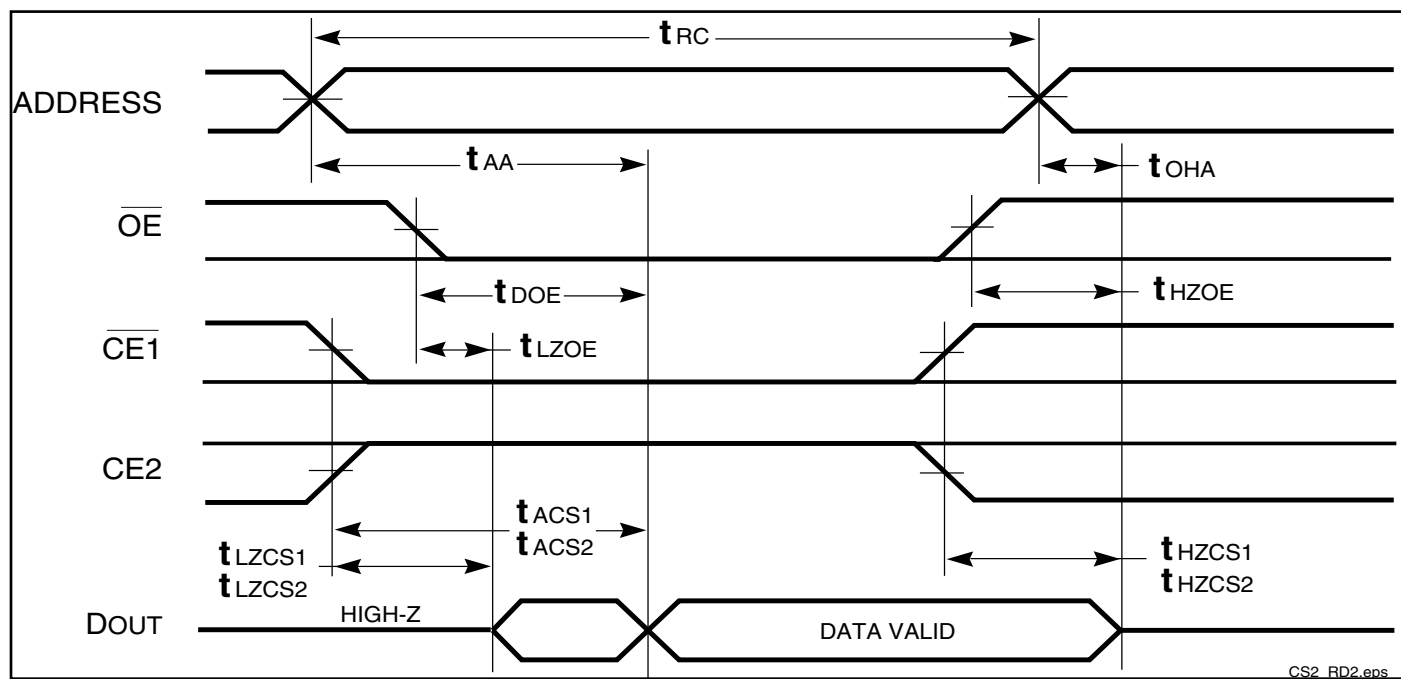
1. Test conditions assume signal transition times of 2 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 200 mV from steady-state voltage. Not 100% tested.

AC WAVEFORMS

READ CYCLE NO. 1^(1,2) (Address Controlled) ($\overline{CE1} = \overline{OE} = V_{IL}$; $CE2 = V_{IH}$)



READ CYCLE NO. 2^(1,3)



Notes:

1. \overline{WE} is HIGH for a Read Cycle.
2. The device is continuously selected. \overline{OE} , $\overline{CE1} = V_{IL}$. $CE2 = V_{IH}$.
3. Address is valid prior to or coincident with $\overline{CE1}$ LOW and CE2 HIGH transition.

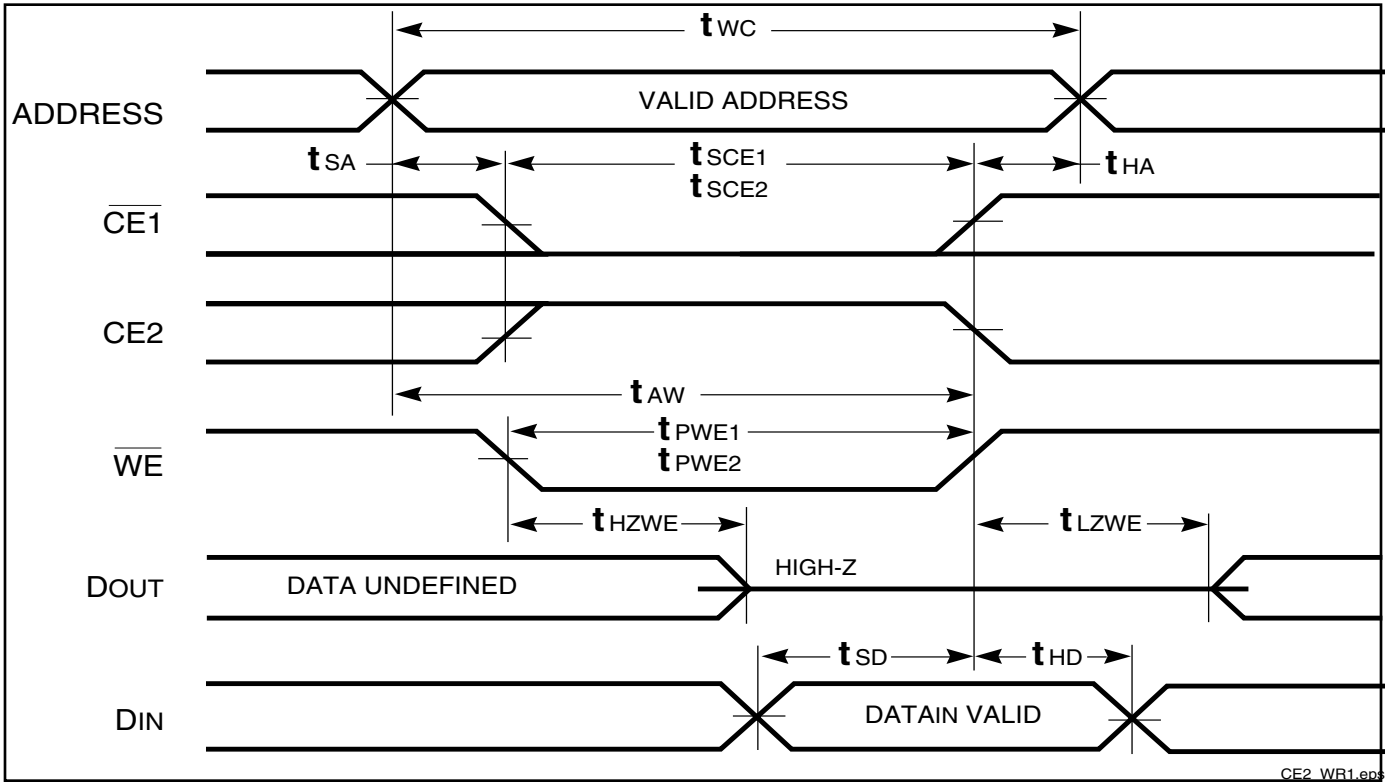
WRITE CYCLE SWITCHING CHARACTERISTICS^(1,3) (Over Operating Range)

Symbol	Parameter	-8		-10		Unit
		Min.	Max.	Min.	Max.	
t _{wc}	Write Cycle Time	8	—	10	—	ns
t _{sce}	$\overline{CE1}$ to Write End	6.5	—	8	—	ns
t _{sce2}	CE2 to Write End	6.5	—	8	—	ns
t _{aw}	Address Setup Time to Write End	6.5	—	8	—	ns
t _{ha}	Address Hold from Write End	0	—	0	—	ns
t _{sa}	Address Setup Time	0	—	0	—	ns
t _{pwe1}	\overline{WE} Pulse Width ($\overline{OE} = \text{HIGH}$)	6.5	—	8	—	ns
t _{pwe2}	\overline{WE} Pulse Width ($\overline{OE} = \text{LOW}$)	8	—	10	—	ns
t _{sd}	Data Setup to Write End	5	—	6	—	ns
t _{hd}	Data Hold from Write End	0	—	0	—	ns
t _{hzwe⁽²⁾}	\overline{WE} LOW to High-Z Output	—	3.5	—	5	ns
t _{lzwe⁽²⁾}	\overline{WE} HIGH to Low-Z Output	2	—	2	—	ns

Notes:

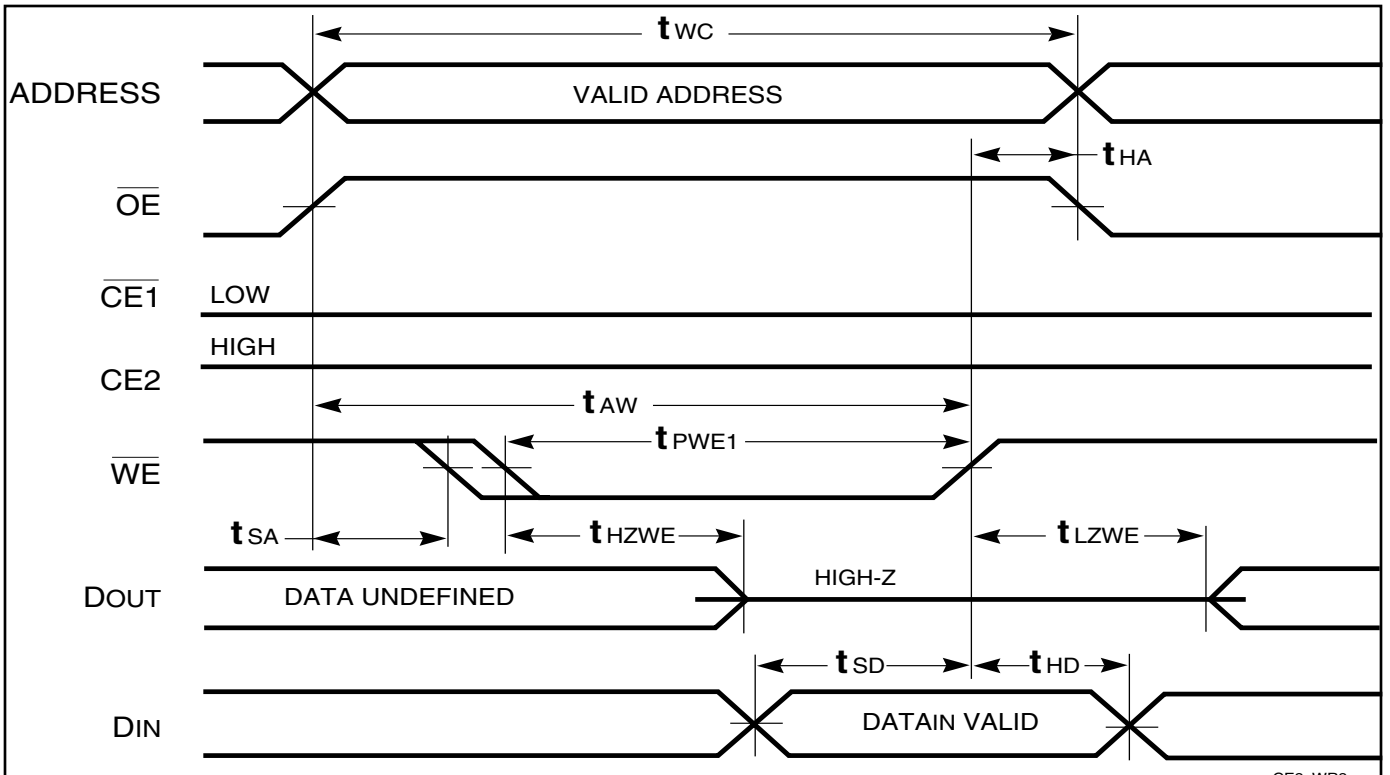
1. Test conditions assume signal transition times of 1.5 ns or less, timing reference levels of $V_{DD}/2$, input pulse levels of 0.4v to $V_{DD}-0.3V$ and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 200 mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of $\overline{CE1}$ LOW, CE2 HIGH and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.

WRITE CYCLE NO. 1 (\overline{CE} Controlled, $\overline{OE} = \text{HIGH or LOW}$)



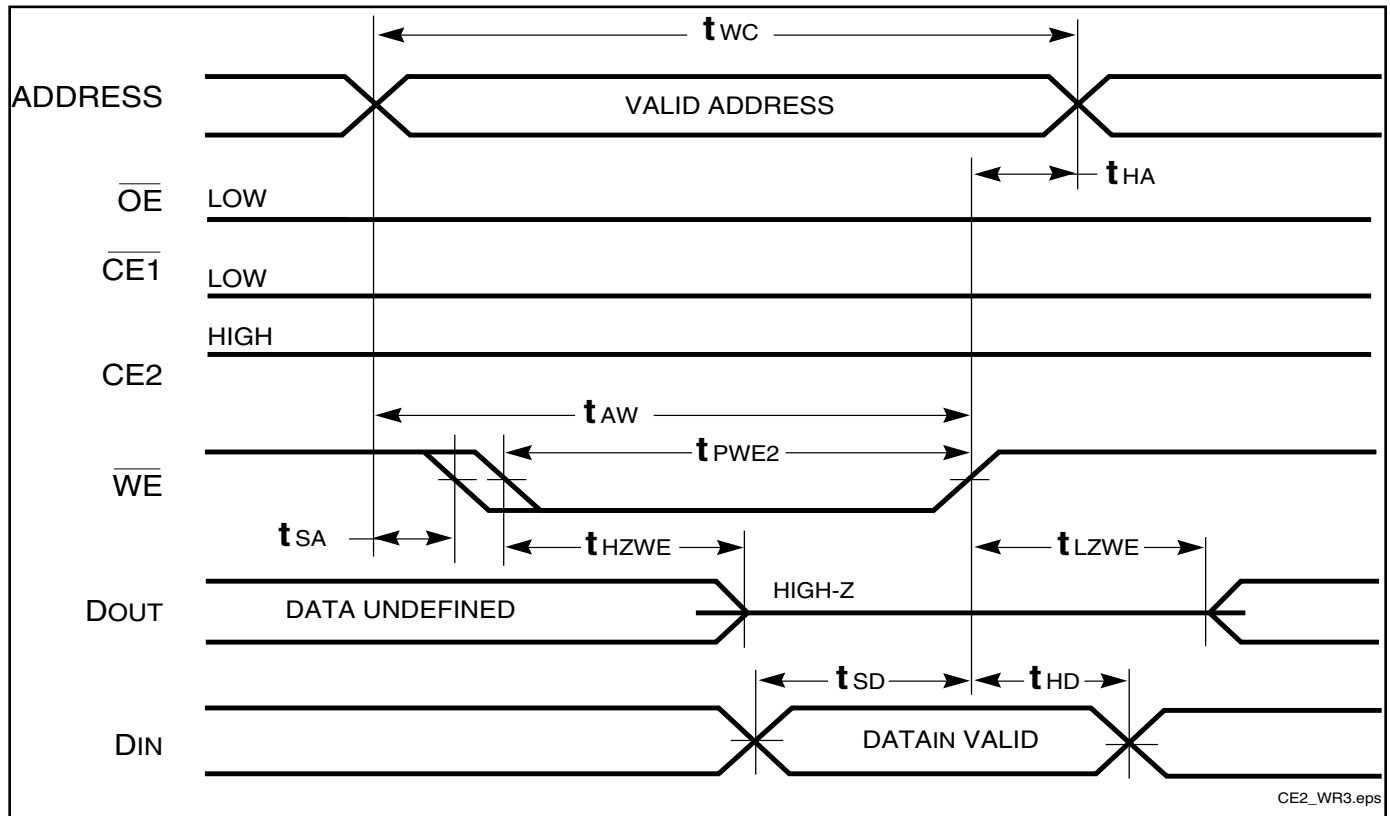
CE2_WR1.eps

WRITE CYCLE NO. 2⁽¹⁾ (\overline{WE} Controlled: $\overline{OE} = \text{HIGH during Write Cycle}$)



CE2_WR2.eps

WRITE CYCLE NO. 3⁽¹⁾ (\overline{WE} Controlled: \overline{OE} IS LOW DURING WRITE CYCLE)



Note:

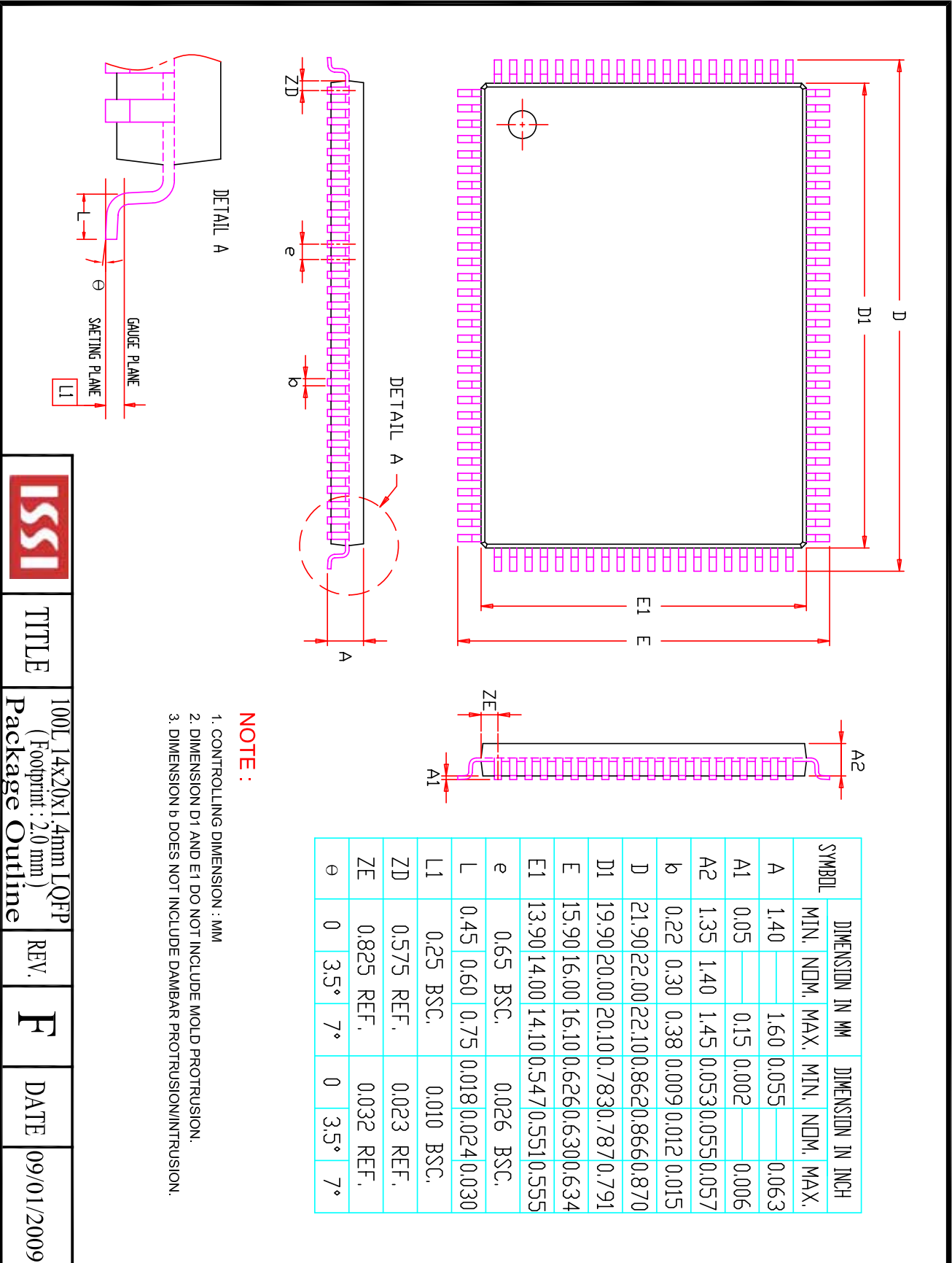
1. The internal Write time is defined by the overlap of $\overline{CE1} = \text{LOW}$, $\text{CE2} = \text{HIGH}$ and $\overline{WE} = \text{LOW}$. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The Data Input Setup and Hold timing is referenced to the rising or falling edge of the signal that terminates the Write.

ORDERING INFORMATION**Commercial Range: 0°C to +70°C**

Speed (ns)	Order Part No.	Package
8	IS61WV12824-8B	Ball Grid Array
	IS61WV12824-8BL	Ball Grid Array, Lead-free
	IS61WV12824-8TQL	QFP, Lead-free
10	IS61WV12824-10B	Ball Grid Array
	IS61WV12824-10BL	Ball Grid Array, Lead-free
	IS61WV12824-10TQL	QFP, Lead-free

Industrial Range: -40°C to +85°C

Speed (ns)	Order Part No.	Package
8	IS61WV12824-8BI	Ball Grid Array
10	IS61WV12824-10BI	Ball Grid Array
	IS61WV12824-10TQLI	QFP, Lead-free



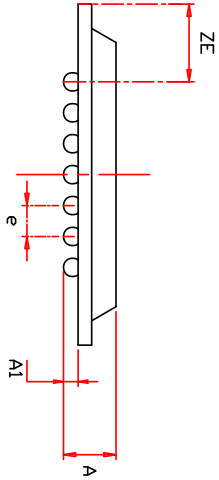
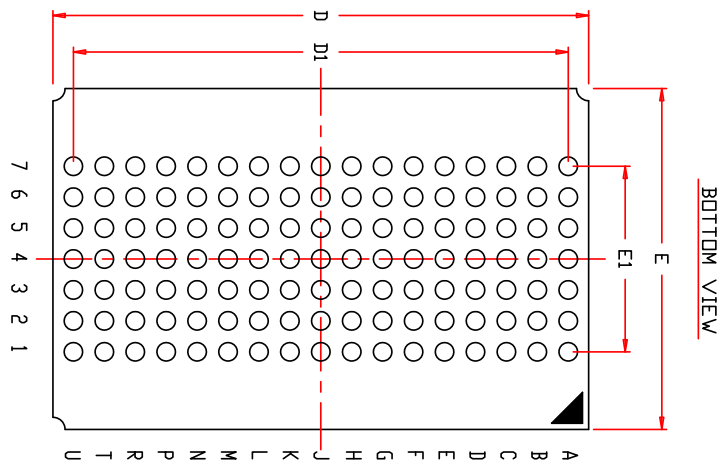
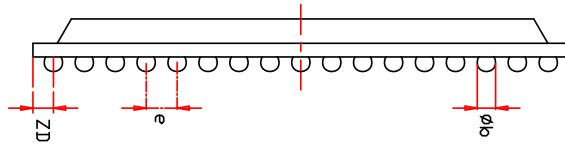
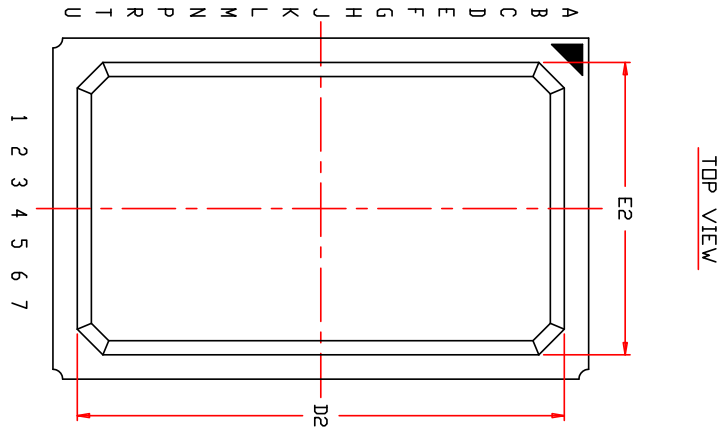
SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.40		1.60	0.055		0.063
A1	0.05		0.15	0.002		0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
b	0.22	0.30	0.38	0.009	0.012	0.015
D	21.90	22.00	22.10	0.862	0.866	0.870
D1	19.90	20.00	20.10	0.783	0.787	0.791
E	15.90	16.00	16.10	0.626	0.630	0.634
E1	13.90	14.00	14.10	0.547	0.551	0.555
e	0.65	BSC.		0.026	BSC.	
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	0.25	BSC.		0.010	BSC.	
ZD	0.575	REF.		0.023	REF.	
ZE	0.825	REF.		0.032	REF.	
theta	0	3.5°	7°	0	3.5°	7°

NOTE :

1. CONTROLLING DIMENSION : MM
2. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.

ISSI	TITLE	100L 14x20x1.4mm LQFP	REV.	F	DATE	09/01/2009
	Package Outline	(Footprint : 2.0 mm)				

280-600-011 REV. A



NOTE :

1. CONTROLLING DIMENSION : MM .
2. Reference document : JEDEC MS-028

SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN.	MAX.	MIN.	MAX.
A	2.15	3.50	-	0.085-0.138
A1	0.50	0.60	0.70	0.020-0.024
phi_b	0.66	0.76	0.86	0.026-0.030
D	21.80	22.00	22.00	0.858-0.866
D1	20.32	BSC.	0.800	BSC.
D2	19.40	19.50	19.60	0.764-0.768
E	13.80	14.00	14.20	0.543-0.551
E1	7.62	BSC.	0.300	BSC.
E2	11.90	12.00	12.10	0.469-0.472
e	1.27	BSC.	0.050	BSC.
ZD	0.84	REF.	0.033	REF.
ZE	3.19	REF.	0.126	REF.



TITLE 119L 14x22mm PBGA Package Outline

REV.

E

DATE

10/13/2010